Application No.: 10/584,822 Docket No.: 17063/007001

REMARKS

Please reconsider this application in view of the above amendments and the

following remarks. Applicant thanks the Examiner for indicating that claims 13-16 contain

allowable subject matter.

Priority Acknowledgement

At the outset, Applicant notes that receipt of the certified copies of the priority

documents at box 12 of the pending office action summary page is incomplete. The Examiner

checked box 12 indicating acknowledgement of the claim for priority and checked box a)

thereunder indicating "all" but did not check any of boxes 1, 2, or 3, thereunder to indicate what

was received. Appropriate indication of acknowledgement of the receipt of all priority

documents is respectfully requested.

Disposition of the Claims

Claims 12-16 are now pending in this application. Claims 12 and 13 are

independent. The other claims depend, directly or indirectly, from claim 13.

Amendments to the Claims

Claim 12 has been amended by way of this reply to clarify the claimed invention.

Additionally, claims 1-11 and 17-18 have been canceled without prejudice or disclaimer. No

new matter has been added by these amendments. Support may be found in the original claims

and the specification as filed.

Rejection(s) under 35 U.S.C. § 102

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Claim 12 stands rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,395,446 ("Kageyama"). For the following reasons, this rejection is respectfully traversed.

Anticipation under 35 U.S.C. § 102(b) requires that the reference teach every aspect of the claimed invention, either explicitly or implicitly. Any feature not directly taught must be inherently present. *See* MPEP § 2131.

Referring to the specification for purposes of illustration only, one or more embodiments of the present invention relate to a recovery tool for attaching a droplet to an edge of a substrate and moving the droplet along the edge in order to inspect the substrate. See paragraph [0001] of the published specification. The recovery tool 30a causes a droplet to come into contact with an edge of a substrate and includes a cylindrical section 31a and a flange section 33a. The cylindrical section 31a has an internal space H capable of accumulating a droplet and has a central axis oriented vertically. The cylindrical section 31a is provided at a side section with a groove 32a being larger in width than the thickness of the substrate, extending horizontally, and connecting the internal space H with an atmospheric space. A drive mechanism is capable of holding the recovery tool 30a so that a droplet exposed to the groove 32a is brought into contact with the edge of the substrate. See paragraphs [0101]-[0104] of the published specification.

Accordingly, amended independent claim 12 recites, in part, a "recovery tool, for adhering a droplet to a substrate and causing movement in order to inspect the substrate, comprising: a cylindrical section with a central axis oriented vertically, having an internal space

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capable of accumulating a droplet, wherein the cylindrical section is provided at a side section with a groove extending horizontally to connect the internal space to atmospheric space, wherein a width of the groove is larger than a thickness of the substrate, and wherein the droplet is adhered to an edge of the substrate."

Kageyama relates to a semiconductor treatment apparatus for recovering impurities on the surface of a semiconductor substrate. See column 1, lines 13-16 of Kageyama. Kageyama discloses that a liquid-drop 14 is provided by, for example, 25 liquid-drop retainer sections 10 of the liquid-drop applicator 8, which is located above the center of the substrate 12. The substrate supporting device 6 and the liquid-drop applicator 8 are rotated in a cooperating manner, and the liquid-drop 14 retained by the retainer 10 is caused to apply to the entire surface of the semiconductor substrate 12 spirally from the center to the periphery. As such, Kageyama merely discloses the application of a droplet to a facing surface of a semiconductor in a spiral pattern.

In contrast, amended independent claim 12 requires a recovery tool that causes a droplet to adhere to a substrate and causes movement in order to inspect the substrate. The recovery tool includes a cylindrical section with a central axis oriented vertically, having an internal space capable of accumulating a droplet. The cylindrical section is provided at a side section with a groove extending horizontally to connect the internal space to atmospheric space. Advantageously, "a width of the groove is larger than a thickness of the substrate" and "the droplet is adhered to an edge of the substrate." Kageyama fails to show or suggest, at least, the above-noted limitations of amended independent claim 12.

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In view of the above, Kageyama fails to show or suggest each and every

limitation of amended independent claim 12. Thus, claim 12 is patentable over Kageyama for at

least the reasons set forth above. Accordingly, withdrawal of this rejection is respectfully

requested.

Conclusion

Applicant believes this reply is fully responsive to all outstanding issues and

places this application in condition for allowance. If this belief is incorrect, or other issues arise,

the Examiner is encouraged to contact the undersigned or his associates at the telephone number

listed below. Please apply any charges not covered, or any credits, to Deposit Account 50-0591

(Reference Number 17063/007001).

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Respectfully submitted,

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